



## EC Declaration of Conformity (DoC)

**We**

Texas Instruments Incorporated  
 12500 TI Boulevard  
 Dallas, Texas 75243 USA

**Declare that the DoC is issued under our sole responsibility and belongs to the following product(s):**

<b>Marketing Name:</b>	SimpleLink™ Wi-Fi® CC3220MOD Wireless Microcontroller Module
<b>Equipment Name:</b>	2.4GHz Wi-Fi® Module
<b>Model Number:</b>	CC3220MODSM2MOB
<b>SW Version:</b>	2.2.0.5
<b>HW Version:</b>	Rev A

**The object of the declaration described above is in conformity with the relevant Union harmonization legislation:**

Radio Equipment Directive 2014/53/EU  
 RoHS2 Directive 2011/65/EU

**Accessories information:**

**Antennas**

List				
	Brand	Antenna Type	Model	2.4GHz gain
1	FoxCon	PCB	T77H533	2.5dBi
2	Ethertronics	Dipole	1000423	-0.6dBi
3	LSR	Rubber Whip / Dipole	001-0012	2dBi
4			080-0013	2dBi
5			080-0014	2dBi
6		PIFA	001-0016	2.5dBi
7			001-0021	2.5dBi
8	Laird	PCB	CAF94504	2dBi
9			CAF94505	2dBi
10	ACX	Multilayer Chip	AT3216-BR2R7HAA	0.5dBi
11			AT312-T2R4PAA	1.5dBi
12	TDK	Multilayer Ceramic Chip Antenna	ANT016008LCD2442MA1	1.6dBi
13			ANT016008LCD2442MA2	2.5dBi
14	Mitsubishi Material	Chip Antenna	AM03DP-ST01	1.6dBi
15		Antenna Unit	UB18CP-100ST01	-1.0dBi
16	Taiyo Yuden	Chip Antenna / Herical Monopole	AF216M245001	1.5dBi
17		Chip Antenna / Monopole Type	AH212M245001	1.3dBi
18			AH316M245001	1.9dBi
19	Antenna Technology	Dipole	AA2402SPU	2.0dBi
20			AA2402RSPU	2.0dBi

21			AA2402A-UFLLP	2.0dBi
22			AA2402AU-UFLLP	2.0dBi
23	Staf	Mono-pole	1019-016	2.14dBi
24			1019-017	2.14dBi
25			1019-018	2.14dBi
26			1019-019	2.14dBi
27	Map Electronics	Rubber Whip	MEIWX-2411SAXX-2400	2.0dBi
28			MEIWX-2411RSXX-2400	2.0dBi
29			MEIWX-282XSAXX-2400	2.0dBi
30			MEIWX-282XRSXX-2400	2.0dBi
31			MEIWF-HP01RS2X-2400	2.0dBi
32	Yageo	Chip	ANT3216A063R2400A	1.69dBi
33	Mag Layers Scientific	Chip	LTA-3216-2G4S3-A1	1dBi
34			LTA-3216-2G4S3-A3	2dBi
35	Advantech	Rubber Whip / Dipole	AN2450-5706RS	2.38dBi

**The following harmonized standards and technical specifications have been applied:**

EN 301489-1 V2.1.1	ElectroMagnetic Compatibility (EMC) standard for radio equipment and services; Part 1: Common technical requirements; Harmonised Standard covering the essential requirements of article 3.1(b) of the Directive 2014/53/EU and the essential requirements of article 6 of the Directive 2014/30/EU;
EN 301489-17 V3.1.1	ElectroMagnetic Compatibility (EMC) standard for radio equipment and services; Part 17: Specific conditions for Broadband Data Transmission Systems; Harmonised Standard covering the essential requirements of article 3.1(b) of Directive 2014/53/EU
EN 300328 v2.1.1	Wideband transmission systems; Data transmission equipment operating in the 2,4 GHz ISM band and using wide band modulation techniques; Harmonised Standard covering the essential requirements of article 3.2 of Directive 2014/53/EU
EN 62311:2008	Assessment of electronic and electrical equipment related to human exposure restrictions for electromagnetic fields (0 Hz - 300 GHz)
EN 60950-1:2006+A11:2009+A1:2010+A12:2011+A2:2013	Information technology equipment – Safety-Part 1: General requirements
EN 50581:2012	Technical documentation for the assessment of electrical and electronic products with respect to the restrictions of hazardous substances



**Notified Body:**

<b>Notified Body:</b>	PHOENIX TESTLAB GMBH
<b>Notified Body Number</b>	700
<b>Reference number of the certificate of notified body</b>	17-211764

**Technical Compliance File Held by:**

Texas Instruments Incorporated  
12500 TI Boulevard  
Dallas, Texas 75243 USA

**Signed for and on behalf of Texas Instruments Incorporated**

<b>Name:</b>	Mattias Lange, General Manager
<b>Address:</b>	12500 TI Boulevard., Dallas Texas, 75243 USA

DALLAS, TX

Place of issue

6/30/17

Date of issue

*Mattias Lange*

Signature of Authorized Person

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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